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(54) Title: ELECTRONIC PACKAGE WITH ENHANCED PAD DESIGN

(57) Abstract

An electronic package (400), particularly a BGA, including a circuitized substrate (120) and one or more active devices (110) attached thereon by means of corresponding conductive pads provided on a surface of the substrate (120); each conductive pad is splitted in a plurality of parts (212-218) not in contact. Such parts (212-218) may be separated by a wireable area of the substrate (120), thereby providing one or more wiring channels. In addition, the same parts (212-218) may be connected in interfacing couples at different electrical potentials (ground and power) and decoupled to each other by means of capacitors (410); the connections to the ground and power are achieved by metallized holes provided through the substrate (120).

